

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

Product data sheet

VOLTAGE RANGE

20 to 100 Volts

CURRENT

3.0 Ampere



FEATURES

- * Ideal for surface mount applications
- * Easy pick and place
- * Built-in strain relief
- * Low forward voltage drop

MECHANICAL DATA

- * Case: Molded plastic
- * Epoxy: UL 94V-0 rate flame retardant
- * Metallurgically bonded construction
- * Polarity: Color band denotes cathode end
- * Mounting position: Any

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
 Single phase half wave, 60Hz, resistive or inductive load.
 For capacitive load, derate current by 20%.

P/N(MARK)	SS32F	SS33F	SS34F	SS35F	SS36F	SS38F	SS39F	SS310F	UNITS
Maximum Recurrent Peak Reverse Voltage	20	30	40	50	60	80	90	100	V
Maximum RMS Voltage	14	21	28	35	42	56	63	70	V
Maximum DC Blocking Voltage	20	30	40	50	60	80	90	100	V
Maximum Average Forward Rectified Current At T _L =100°C	3.0								A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	80								A
Maximum Instantaneous Forward Voltage at 3.0A	0.55			0.70		0.85			V
Maximum DC Reverse Current Ta=25°C	0.1					0.02			mA
at Rated DC Blocking Voltage Ta=100°C	5					2			mA
Typical Junction Capacitance (Note1)	300								pF
Typical Thermal Resistance R _{JL} (Note 2)	10								°C/W
Operating Temperature Range T _J	-65 — +150								°C
Storage Temperature Range T _{STG}	-65 — +150								°C

NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. Thermal Resistance Junction to Lead.

RATING AND CHARACTERISTIC CURVES (SS32F THRU SS310F)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

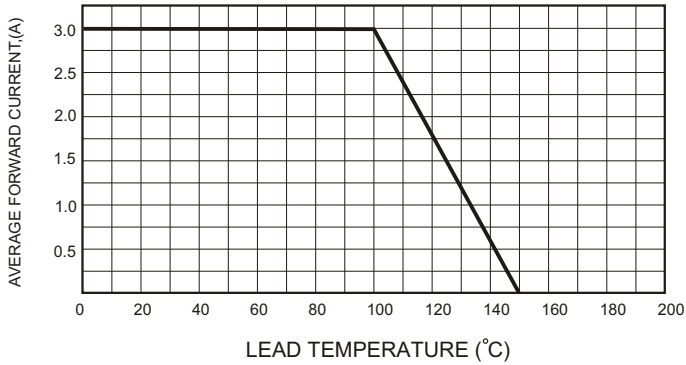


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

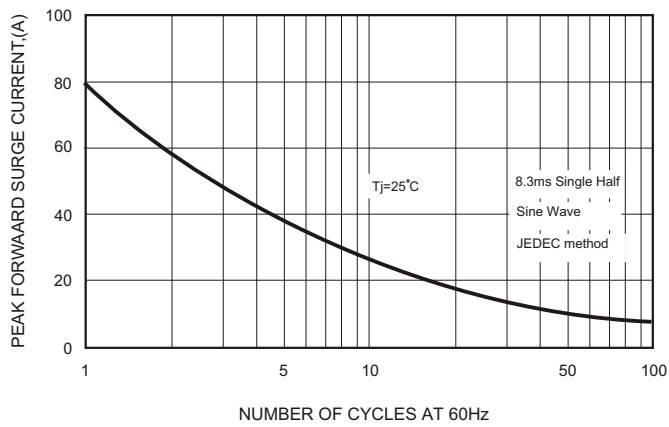


FIG.4-TYPICAL JUNCTION CAPACITANCE

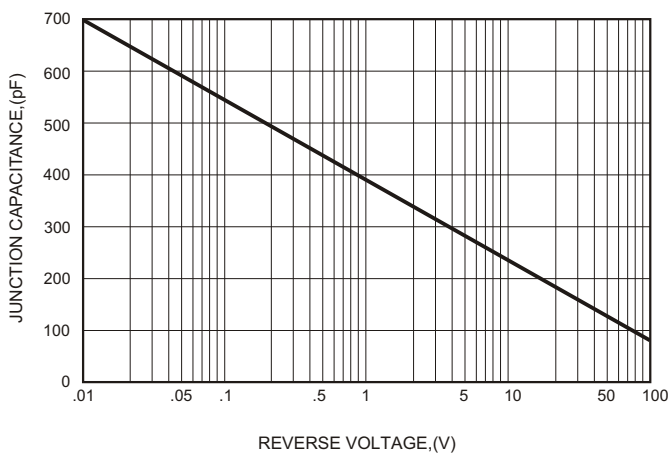


FIG.2-TYPICAL FORWARD CHARACTERISTICS

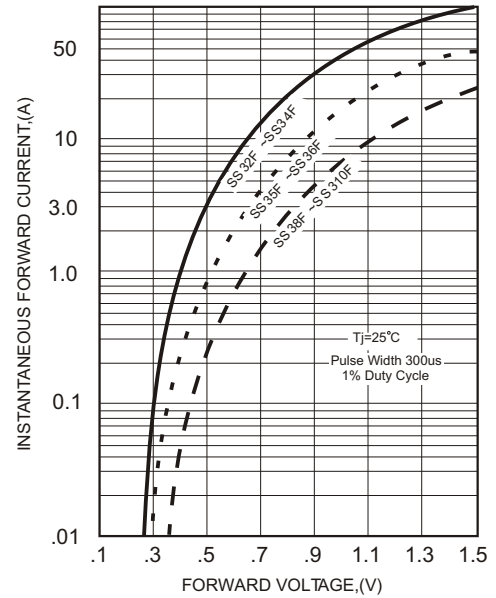
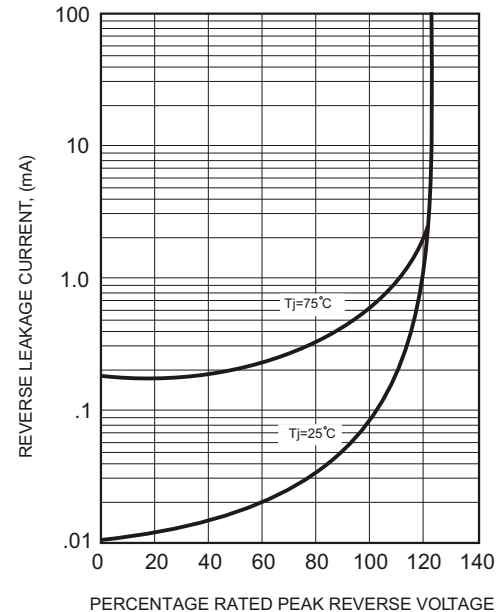
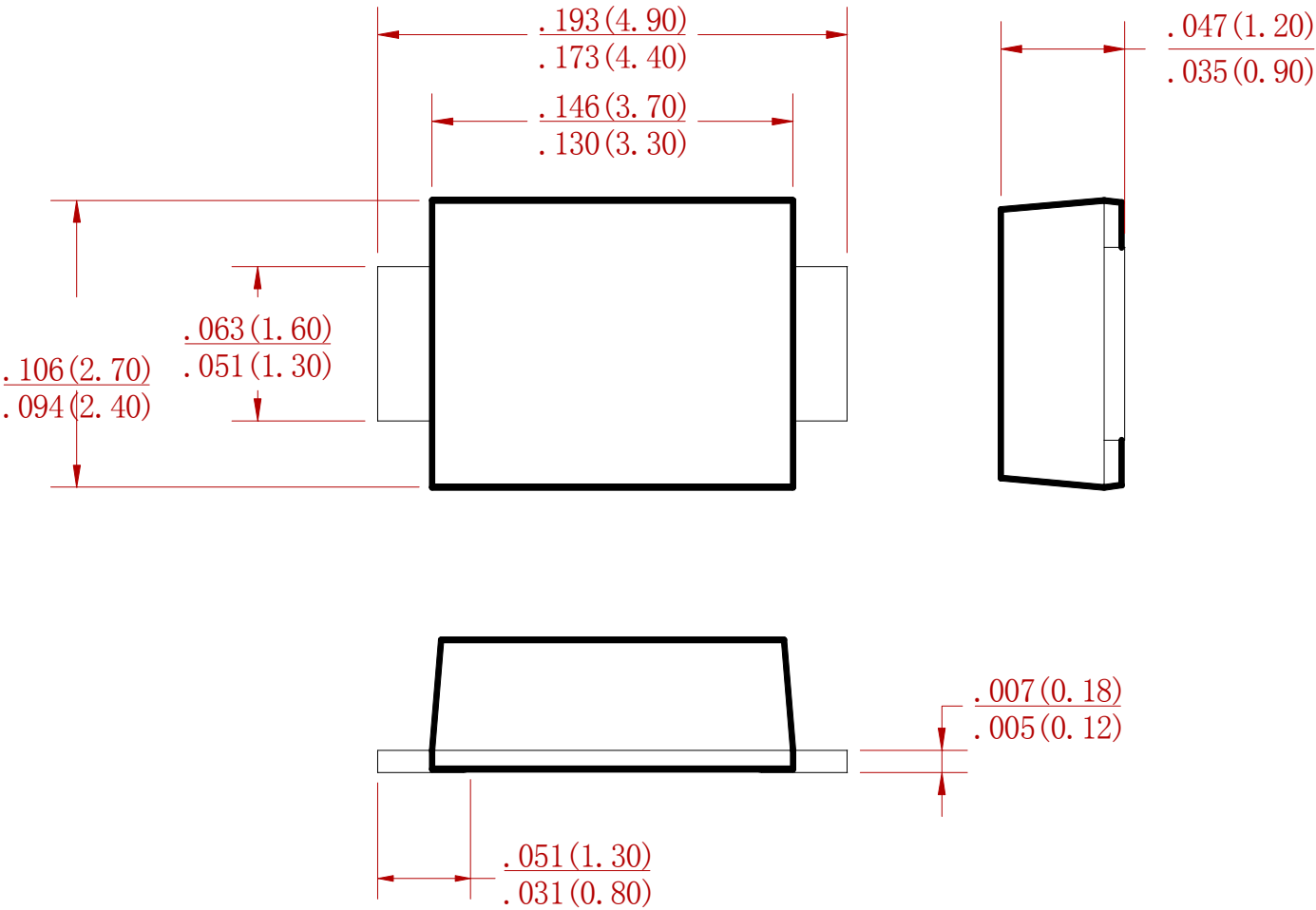


FIG.5 - TYPICAL REVERSE CHARACTERISTICS



PACKAGE MECHANICAL DATA



Dimensions in inches and (millimeters)

REEL SPECIFICATION

P/N	PKG	QTY
SS32F THRU SS310F	SMAF	3000

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